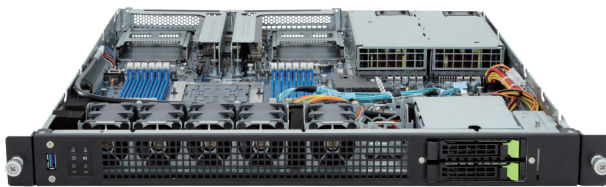


E163-Z30-AAG1

Edge Server - 1U UP 2-Bay NVMe/SATA



Key Features

- Single AMD EPYC™ 9004 Series Processors
- 12-Channel DDR5 RDIMM, 12 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 2 x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 1 x M.2 slot with PCIe Gen3 x4 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 1+1 800W 80 PLUS Titanium redundant power supplies

Application

Networking, Edge, Hybrid/Private Cloud Server...

Specification

Dimensions 1U (W438 x H43.5 x D520 mm)

Motherboard MZ33-DC0

CPU AMD EPYC™ 9005 Series Processors
AMD EPYC™ 9004 Series Processors
Single processor, cTDP up to 300W
- At 30°C ambient, cTDP up to 400W

Sock 1 x LGA 6096 (Socket SP5)

Chipset System on Chip

Memory 12 x DIMM slots
12-Channel DDR5 RDIMM
Up to 4800 MT/s

LAN 1 x 1Gb/s LAN (1 x Intel® I210-AT) - Supports NCSI function
1 x 10/100/1000 Mbps Management LAN

Video Integrated in ASPEED® AST2600
- 1 x Mini-DP

Storage Front hot-swap:
2 x 2.5" Gen4 NVMe/SATA/SAS
*SAS card is required to support SAS drives.
Internal M.2:
1 x M.2 (2280/22110), PCIe Gen3 x4

RAID Require RAID add-in cards

Expansion Slots 2 x FHHL PCIe Gen5 x16 slots
2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Supports NCSI function

I/O Ports Front: 1 x USB 3.2 Gen1
Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN

Backplane Board Speed and bandwidth:
PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s

Security Modules 1 x TPM header with SPI interface
- Optional TPM2.0 kit: CTM010

Power Supply 1+1 800W 80 PLUS Titanium redundant power supplies
AC Input: 100-240V

System Management ASPEED® AST2600 Baseboard Management Controller
GIGABYTE Management Console web interface

OS Support Windows Server, Red Hat Enterprise Linux server, Ubuntu,
SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor

System Fans 5 x 40x40x56mm (30,000rpm)

Operating Properties Operating temperature: 10°C to 35°C
Operating humidity: 8%-80% (non-condensing)
Non-operating temperature: -40°C to 60°C
Non-operating humidity: 20%-95% (non-condensing)

Packaging Content 1 x E163-Z30-AAG1, 1 x CPU heatsink,
1 x Mini-DP to D-Sub cable
Packaging Dimensions: 782 x 588 x 212 mm

Part Numbers Barebone package (EPYC 9005/9004): 6NE163Z30DR000ABG1*
Barebone package (EPYC 9004): 6NE163Z30DR000AAG1*
Optional parts:
- 2-Section Rail kit (385-480mm): 25HB2-3A0204-K0R
- 2-Section Rail kit (660-840mm): 25HB2-3A0203-K0R



Learn more at <https://www.GIGABYTE.com/enterprise>

* All specifications are subject to change without notice. Please visit our website for the latest information.
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